TRANSCOM

TC5282C

PRE.2_05/24/2019

27 – 29.5 GHz 0.5W PA Driver MMIC(Chip Form)

FEATURES

- Psat : +27.0dBm
- P1dB : +26.0dBm
- IMD3 : +42.0dBc @ Pscl +14dBm
- Small Signal Gain: 16dB
- Bias Condition: 450mA @ +6V

APPLICATIONS

- New 5G Radio Link
- VSAT
- Sat-Com
- Point-to-Point Radio

DESCRIPTION

The TC5282C is a two-stages PHEMT high power amplifier driver MMIC that operates from 27 to 29.5 GHz. The amplifier provides a typical 16 dB of gain and delivers +27 dBm of Psat. The MMIC is fabricated using Transcom's proprietary matured GaAs PHEMT process. The process features full passivation for increased performance and reliability. All devices are 100 % DC tested to assure consistent quality. Bond pads are gold plated for either thermocompression or thermosonic wire bonding. Backside gold plating is compatible with standard AuSn die-attach.

ELECTRICAL SPECIFICATIONS (Ta = 25 °C)

SYMBOL	DESCRIPTION	MIN	TYP	MAX	UNITS
FREQ	Frequency Range	27		29.5	GHz
SSG	Small Signal Gain		16		dB
Psat	Saturation Output Power		27.0		dBm
P1dB	1dB Compression Output Power		26.0		dBm
IMD3	The Third Intermodulation level at Pout +14dBm/tone, △f=20MHz		42.0		dBc
I.L., IN	Input Return Loss		8		dB
I.L., OUT	Output Return Loss		10		dB
VDD	Supply Voltage		+6		Volt
IDQ	Current Supply Without RF		450		mA
IDRF	Current Supply @ Psat		520		mA

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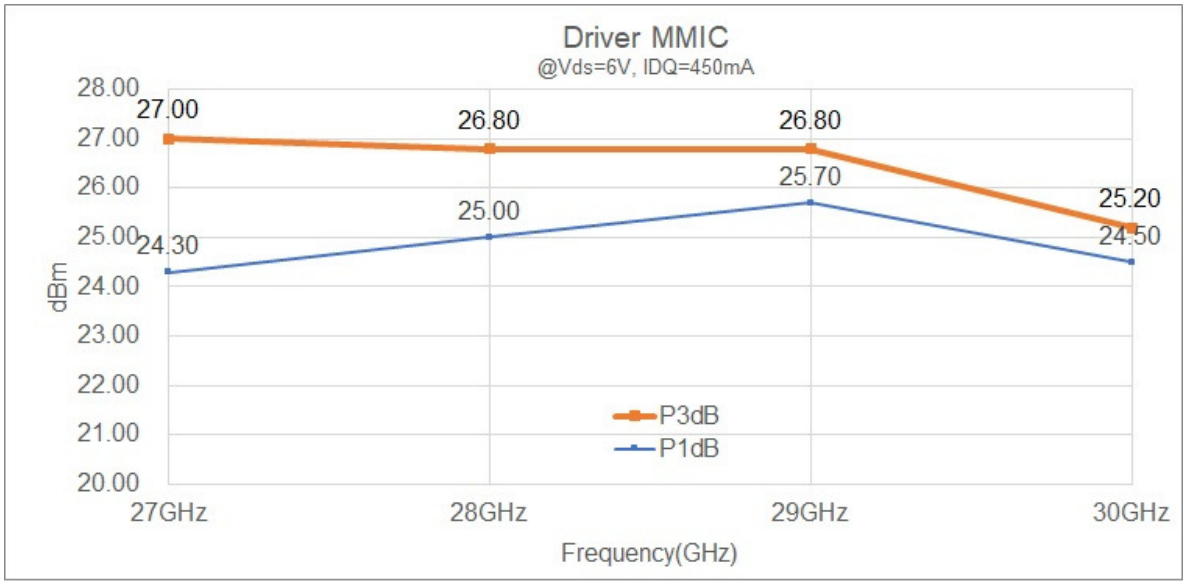
ABSOLUTE MAXIMUM RATINGS

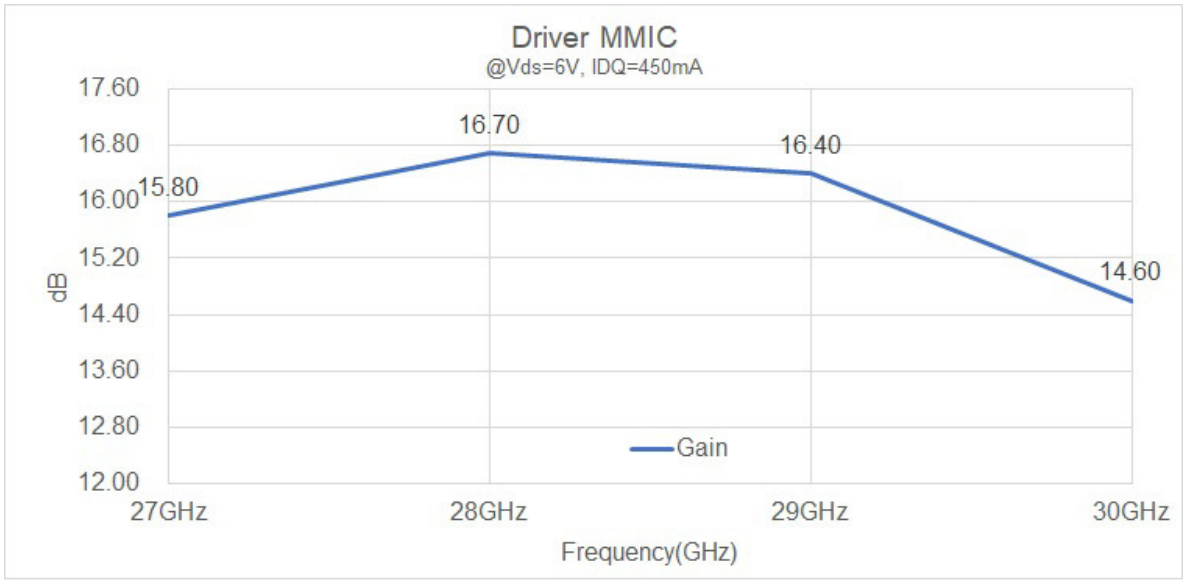
Symbol	Parameter	Rating
V_{DS}	Drain-Source Voltage	7.0 V
I_D	Drain Current	800 mA
P_T	Continuous Dissipation	5.0 W
P_{in}	Input Power, CW	+15 dBm
Tch	Channel Temperature	+175
T_{STG}	Storage Temperature	- 50 °C to +150 °C

TYPICAL CHARACTERISTICS

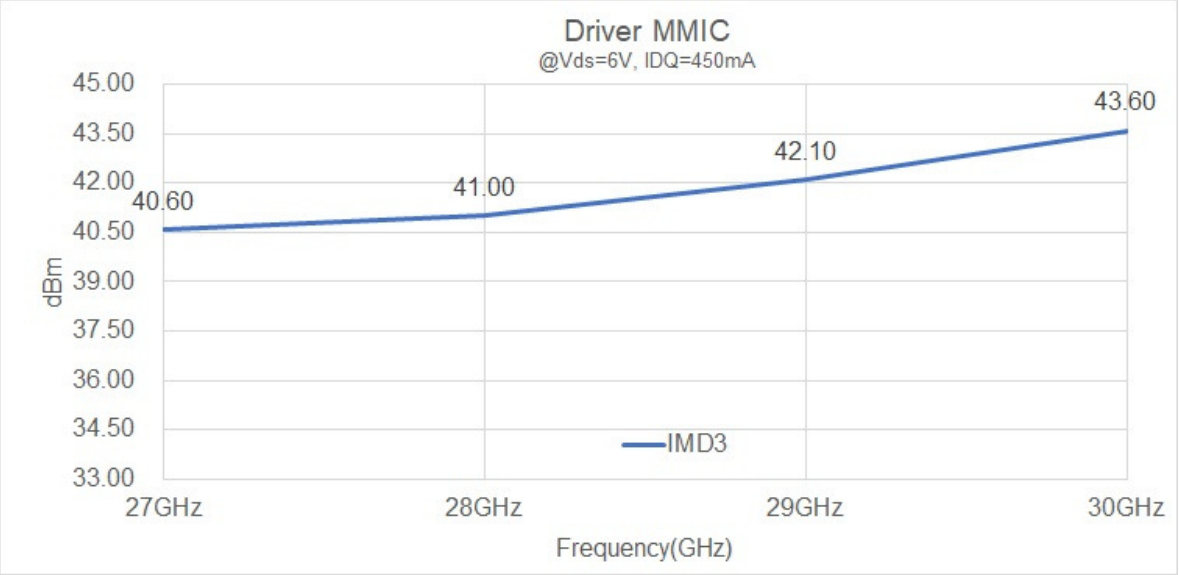
Pout vs Freq.



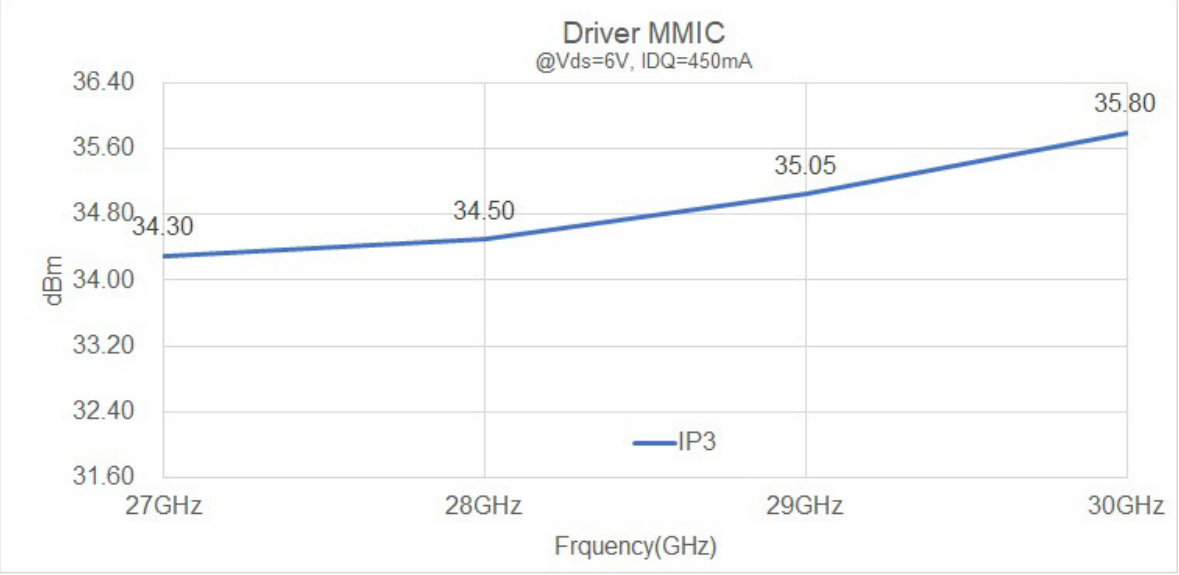
Gain vs Freq.



IMD3 vs Freq (@Pscl = +20dBm)

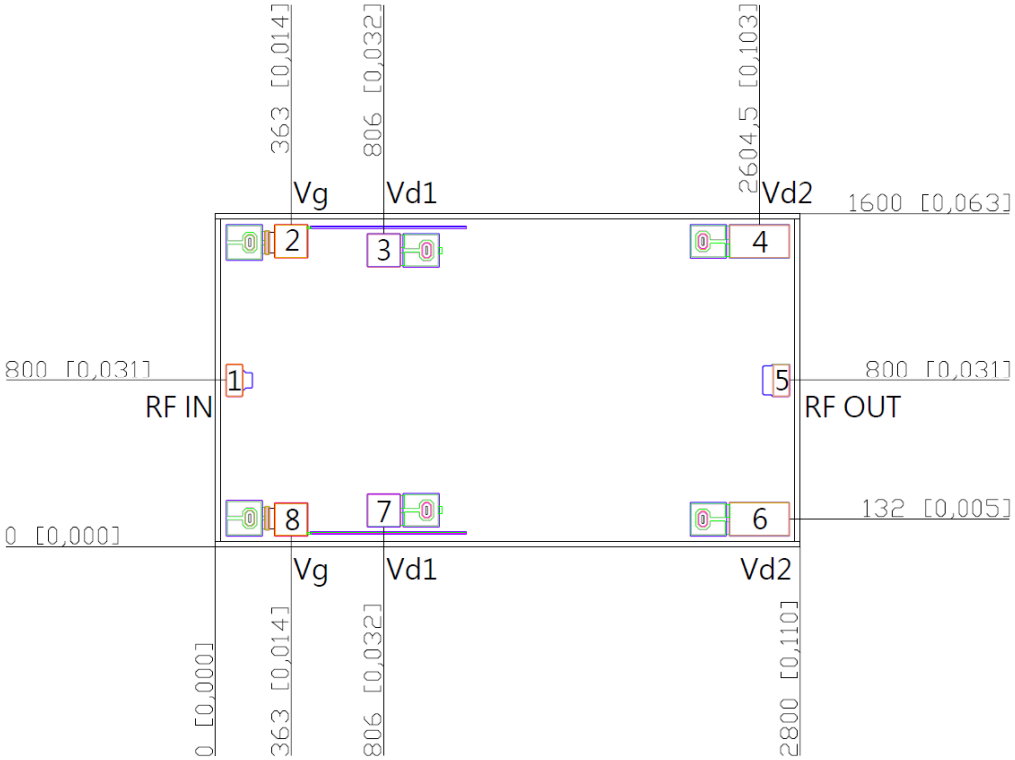


IP3 vs Freq



MECHANICAL OUTLINE

Units: micrometer (inch)
Thickness: 50.8 (0.002)
Chip Size: 2800 ± 50.8 × 1600 ± 50.8 (0.110 ± 0.002 × 0.063 ± 0.002)
Bond pad # 1 (RF IN) 82 × 162 (0.0032 × 0.0063)
Bond pad # 2,8 (Vg) 160 × 160 (0.0062 × 0.0062)
Bond pad # 3,7 (Vd1) 160 × 160 (0.0062 × 0.0062)
Bond pad # 4,6 (Vd2) 162 × 289 (0.0063 × 0.0113)
Bond pad # 5 (RF OUT) 82 × 162 (0.0032 × 0.0063)



ASSEMBLY DIAGRAM

1. Using 1mil Au Wire.
2. Substrate Material : Al2O3
3. Substrate Thickness : 10 mil